

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Units                    |    | MILLIMETERS |     |      |
|--------------------------|----|-------------|-----|------|
| Dimension Limits         |    | MIN         | NOM | MAX  |
| Contact Pitch            | E  | 1.27 BSC    |     |      |
| Contact Pad Width (Xnn)  | X1 |             |     | 0.70 |
| Contact Pad Length (Xnn) | Y1 |             |     | 1.00 |

 Copper Keep-Out Area for Test Point

1. Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. The theoretically exact value is shown without tolerances.
2. For best soldering results, please refer to IPC-7093.